Product Change Notification / ASER-25FYQB098

Date:

15-Feb-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4397 Final Notice: Qualification of MTAI as a new assembly site for selected 24LCxxx, 24AAxxx and 24FCxxx device families available in 8L SOIC (3.90mm) package.

Affected CPNs:

ASER-25FYQB098_Affected_CPN_02152021.pdf
ASER-25FYQB098_Affected_CPN_02152021.csv

Notification Text:

PCN Status: Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section to the right.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .csv).

Description of Change: Qualification of MTAI as a new assembly site for selected 24LCxxx, 24AAxxx and 24FCxxx device families available in 8L SOIC (3.90mm) package.

Pre Change: Assembled at NSEB using HR-5104 die attach and G600 mold compound.

Post Change:
Assembled at MTAI using 8390A and 8006NS die attach and G600 mold compound.

Pre and Post Change Summary:

	Pre Change	**Post Change**
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	Au	Au
Die attach material	HR-5104	8390A / 8006NS
Molding compound material	G600	G600
Lead frame material	CDA194	CDA194

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying MTAI as a new assembly site.

Change Implementation Status: In Progress or complete

Estimated First Ship Date: February 20, 2021 (date code: 2108)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2021			
Workweek	06	07	08	09
Qual Report Availability	X			
Final PCN Issue Date	X			
Estimated Implementation Date			X	

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:February 5, 2020: Issued final notification.**February 8, 2020:** Reissued final notification. Corrected post change to clarify both die attach will be used.**February 15, 2020:** Reissued final notification. Updated the mold compound material in the Post change field to matched with the summary table and Qual Report.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_ASER-25FYQB098_Pre and Post Change Summary.pdf

PCN_ASER-25FYQB098_Qual Report_1 of 3.pdf
PCN_ASER-25FYQB098_Qual Report_2 of 3.pdf
PCN_ASER-25FYQB098_Qual Report_3 of 3.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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